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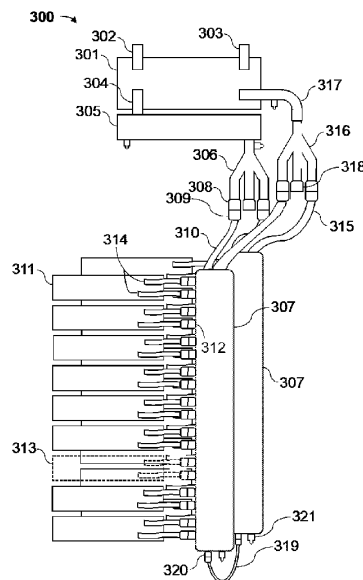


FIG. 3
(Schematic of the two-phase cooling system.)

(57) Abstract: Systems, devices and methods for providing cooling to hardware components, and more specifically to manifold systems, devices and methods for thermal management of hardware in computer server racks and related equipment in computer data centers.

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